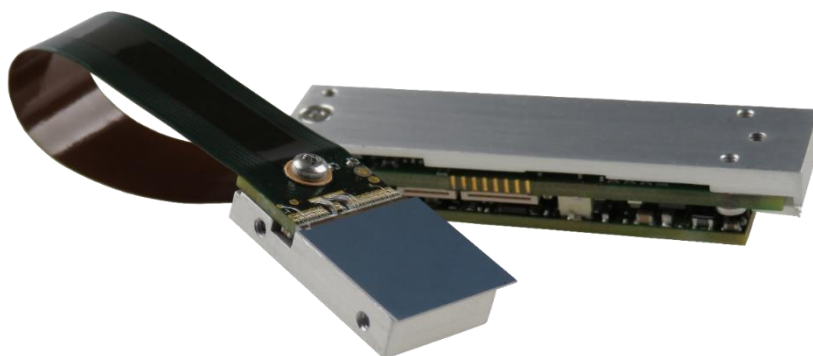


MiniPIX

MAGIC Flex

Model No.: MNXT3F-Xxx190731
MT3Fxx-Xxx190925
MT3F10-Xxx211214
MT3F10-Xxx220422



General features

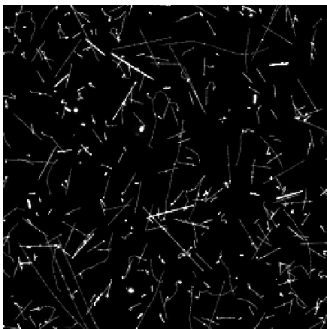


Illustration of single particle sensitivity of Timepix3 detector. The tracks of different particles of radiation background (mostly muons and few protons) were recorded in 5 minutes on board of an airplane. No noise (clean zero) is seen in the dark regions.

The **MiniPIX MAGIC Flex** is a miniaturized and low power radiation camera equipped with particle tracking and imaging detector Timepix3 (256 x 256 square pixels with pitch of 55 μm). Several sensor materials are provided according to customer preference (usually 300 μm thick silicon).

The Timepix3 detector is position, energy and time sensitive: For each ionizing particle (e.g. X-ray photon) it digitally registers its position, energy, time of arrival and track shape - basically all information you could want. The other measures can be calculated from the track shape (particle type, direction of flight, LET, charge...). The information on each detected particle is either read out immediately (pixel mode) at maximal rate of 2,3 million hit pixels per second or accumulated in images (frame mode) and read out later at maximal speed of 16 frames per second.

The typical and intended applications of **MiniPIX MAGIC Flex** are:

- **Spectral X-ray imaging:** XRF imaging, X-ray radiography (low flux).
- **Energy dispersive XRD, SAXS or WAXS:** Monochromatic X-ray source is NOT needed! Even high energy for thick samples is possible (e.g. 100 keV)!
- **Spectral gamma ray imaging:** Scintigraphy or SPECT, radiography with isotopes.
- **Radiation monitor¹:** Particle type sorting, spectroscopy, directional sensitivity.
- **Gamma camera:** Special shielded box and collimators are available upon request.
- **Compton camera:** Gamma ray imaging based on Compton scattering (special software module for image reconstruction is required).

The **MiniPIX MAGIC Flex** device is controlled via USB 2.0 interface with standard μUSB connector. Complex PIXet Pro software for detector operation is provided together with the device. All major operating systems are supported (MS Windows, Mac OS and LINUX). Extra software modules are available for special functions (e.g. spectrum filtering and reconstruction, coded aperture image reconstruction, Compton camera image and spectrum reconstruction, radiation field decomposition, networking of many devices...).

Main Features

- Readout chip type..... Timepix3
- Pixel size²..... 55 x 55 μm^2
- Sensor resolution..... 256 x 256 pixels
- Time resolution 1,6 ns
- Dynamic range in one frame³..... 1022
- Sensor material..... 300, 500 μm Si, 1000 μm CdTe
- Dark current..... none
- Interface..... USB 2.0 (High-Speed)
- Maximum readout speed 2,35 million pixels / s
- Dimensions..... see page 8-11
- Weight..... 22 g (CdTe sensor, no cover)

¹ The device is not certified dosimeter. It serves as the first level indicator and monitor of radiation fields allowing identification of a radiation type. Radiation protection of people cannot be based on measurements with this device.

² 55 x 110 μm^2 at the edges and 110 x 110 μm^2 at the corners

³ i.e. counter depth. Dynamic range of integrated picture is theoretically unlimited.

Device parameters

Operation conditions

Symbol	Parameter	Value	Units	Comment
T_a	Operating ambient temperature range ¹	0-50	°C	
Φ	Humidity	< 80	%	Not condensing
IP	IP rating with cover	IP20		For transport purposes
IP	IP rating without cover	IP00		

¹ With temperature stabilization – see the paragraph below.

Vacuum operation

ADVACAM detectors can be vacuum compatible on request. Contact support@advacam.cz for more information.



- In case of vacuum operation, operate only with air pressure lower than 10^{-3} Pa.
- The device will automatically shut down after chip or CPU temperature exceeds 55 °C.
- Intended for dust free indoor use.
- Make sure to disconnect the device from power during pumping down or venting the vacuum chamber!
- A direct connection to the host device is required for maximum performance. Connecting via a USB hub may negatively affect the performance and stability of the device.

External temperature stabilization

Temperature stabilization of the device is strongly recommended for consistent results. Attaching a Peltier cooling or cooling plate at the back of the detector should serve the purpose. The temperature should be set to 22 °C.

Electrical specification

$T_{dev} = 22$ °C, USB voltage $V_{CC} = 4,8$ V

Symbol	Parameter	Min	Typ	Max	Units	Comment
V_{CC}	Supply Voltage	4,0	5,0	5,5	V	Comply with USB 2.0
I_{CC}	Chip active		300	500	mA	Comply with USB 2.0, Mode dependent
P1	Power consumption			2,5	W	

Typical bias voltage source for sensor diode	Si				CdTe		Units
Thickness	100	300	500	1000 ¹	1000	2000 ¹	μm
V_{BIAS} ²	50	150	150	200	-300 to -500	-500	V

¹Customized product

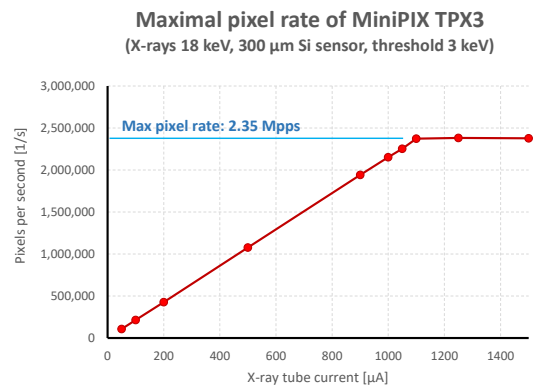
² Positive for Si sensors, negative for CdTe. Typical values

Performance characteristics

Symbol	Parameter	Min	Typ.	Max	Units	Comment
f_f	Frame-rate			16	fps	with USB 2.0 Host
T_{FREAD}	Frame readout time	62			ms	
f_p	Pixel type hit-rate in ToT+ToA mode (pixels per second)			$2,35 \times 10^6$	pps	with USB 2.0 Host

Pixel mode hit-rate measurement

The whole detector is exposed to homogenous direct (perpendicular) irradiation from X-ray tube operated at 18 kVp with 2 mm Aluminum filter. The measurement type is set to “Pixels” and mode to “ToT+ToA”, all other parameters are set to factory defaults (as stored in configuration file delivered with the device). The exposure time is set to 0,1 s. The “Clustering” tool of PIXet Pro is used to analyze measured data. The number of hit pixels per second is drawn as function of X-ray tube current searching for saturation.



Sensor parameters

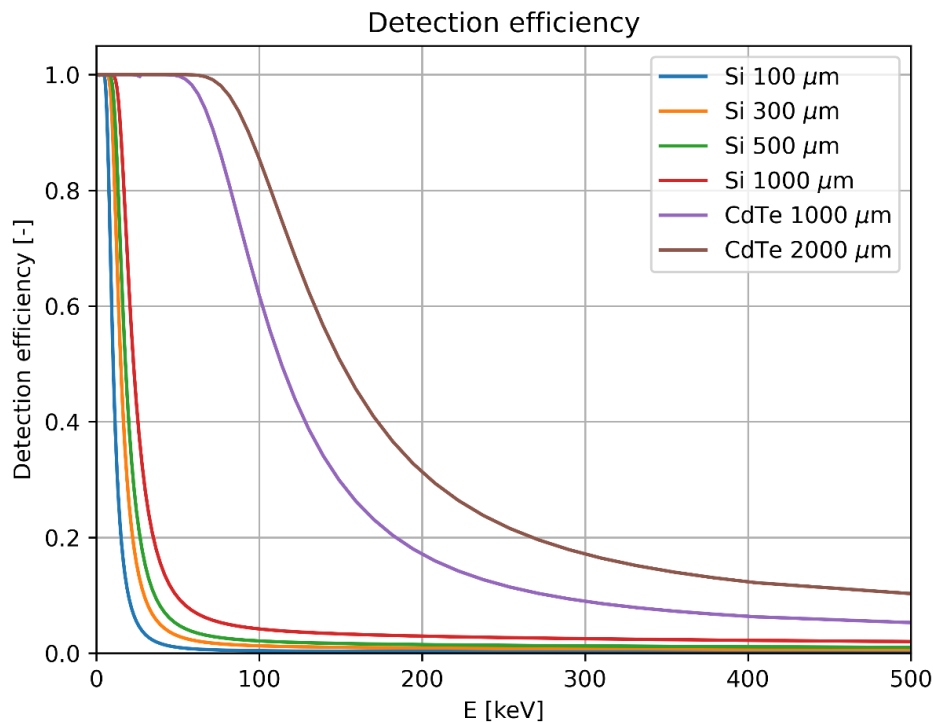
$T_{dev} = 22\text{ °C}$

Parameter	Si				CdTe		Unit s	Comment
Thickness	100	300	500	1000 ¹	1000	2000 ¹	µm	
Calibrated energy threshold ²	3,0	3,0	3,0	3,0	5,0	5,0	keV	
Energy resolution in ToT mode (σ @ 60 keV)	1,2 – 2,6	1,3 – 2,7	1,4 – 3,5	1,7 – 3,6	2,8 – 5,4	2,9 – 8,3	keV	Valid for the standard calibration
Energy resolution in ToT mode (σ @ 122 keV)					3,4 – 6,0	4,5 – 9,9	keV	Valid for the standard calibration
Typical detectable energy range for X-rays	3 – 60				5 – 500		keV	See chart below
Good pixels	> 99,5 %				> 99,5 %			
Pixel size ³	55 x 55						µm	

¹ Customized product

² Premium calibration and/or chip class can achieve even better performance. For more information, please contact support@advacam.cz

³ 55 x 110 µm at the edges and 110 x 110 µm at the corners



Basic principles, measurement types and operational modes

The ionizing radiation particle interacts with the sensor material creating an electric charge. This charge is collected by electric field and brought to pixel preamplifier where it is amplified and shaped forming triangular voltage pulse. The amplitude and duration of this pulse is proportional to energy deposited by particle within the pixel. The situation when the voltage pulse amplitude in particular pixel exceeds preselected threshold value is called “event” or “hit”.

Each pixel contains three digital counters (10, 14 and 4 bits). These counters are used differently according to measurement type and mode. There are four different quantities which can be measured and stored in counters of each pixel – these are selected by operational modes.

Operational modes:

Number of events	= number of events (hits) in the pixel during exposure time (this mode is suitable mainly for frame type readout).
Time-over-Threshold (ToT)	= number of periods of 40 MHz clock signal (25 ns step) when amplifier output signal stays over the energy threshold. The ToT can be transformed to energy in keV using per-pixel-calibration function. The coefficients for per-pixel-calibration are unique for each pixel and they are stored in configuration file delivered with the device. The energy calibration is valid only for given values of other detector parameters as delivered in configuration file (especially threshold)

Time-of-Arrival (ToA) = number of periods of 40 MHz clock signal (25 ns step) from start of exposure till the event is registered by pixel (i.e. pulse in pixel crosses the threshold). The range is 409,6 μ s. Additional 16 bits are added in FPGA in readout electronics so that the total range is 26,8 seconds. An additional counter has also been added to perform scans beyond 26,8 seconds.

Fast-Time-of-Arrival (FToA) = time difference between event detection and next clock signal measured with step of 1,5625 ns. Range is 4 bits. The combination of ToA and FToA gives precise time of event detection in nanoseconds using following formula:

$$\text{Time [ns]} = \text{ToA} \cdot 25 - \text{FToA} \cdot 1,5625$$

Measurement types:

Frame type measurement No data is sent out of device during the exposure time. All measured events are accumulated in counters of pixels. **Event counter** is incremented and ToT is integrated in to **iToT counter** for all events. The measured data is read-out after end of exposure time for all pixels with nonzero content. No measurement can be performed during readout process. Measurement types in PIXet Pro: Frames, Integral.

Pixel type measurement Information about all hit pixels is read-out immediately and continuously during exposure time. If hit rate is below maximal value (see f_p in table of Performance characteristics) then there is practically no deadtime. Measurement type in PIXet Pro: Pixels.

Sometimes this mode is referred to as the data-driven mode or the event-based mode.

Combinations of operation modes and measurement types (rarely used cases are shown with gray background):

Type	Mode	Range	Description
Frames (reading all pixels after end of exposure)	ToA+ToT	18 bit + 10 bit	2 output frames per exposure: ToA = Time of Arrival of first event in pixel, ToA and FToA ¹ combined ToT = Time over Threshold, i.e. energy in keV if calibration is loaded and switched on
	ToA	18 bit	1 output frame: ToA = Time of Arrival of first event in pixel, ToA and FToA ¹ combined
	Event+iToT	10 bit + 14 bit	2 output frames per exposure: Events = number of events in pixel iToT = integrated Time over Threshold, i.e. energy in keV if calibration is loaded and switched on, for all events in pixel
Pixels (reading only hit pixels continuously during exposure)	ToA+ToT	18 bit + 10 bit	Data stream contains 4 values per pixel per event: Position, ToT, ToA and FToA ¹ (for data formats .t3*)
	ToA	18 bit	Data stream contains 3 values per pixel per event: Position, ToA and FToA ¹ (for data formats .t3*)
	Only ToT	10 bit	Data stream contains 2 values per pixel per event: Position and ToT (for data formats .t3*)

¹ ToA and FToA are combined together by software automatically. For Pixel type measurement, if saved as a .t3pa file, ToA and FToA are stored as separate items

Device description

The device is delivered with USB flash disk containing installer of PIXet Pro software, unique device configuration and calibration file and protocol on quality tests.

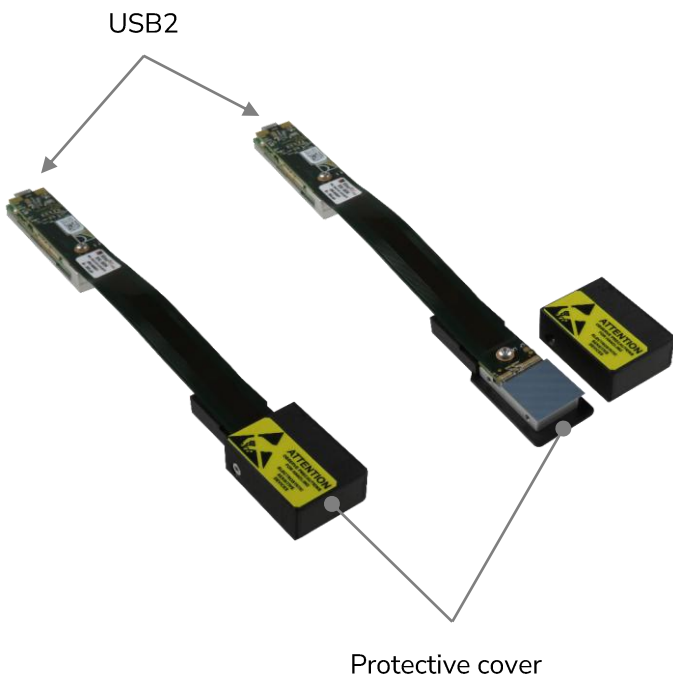
The device casing is made of aluminum with sliding cover made of stainless steel protecting the sensor window. The communication and powering is provided by USB 2.0 Micro-B connector and cable.



- Protective cover must be removed before use to avoid sensor damage from overheating. Remove the cover with extreme care, avoid any contact with the sensor chip or wire-bonds.
- High voltage - Sensor chip is supplied with high voltage up to ± 500 V. To avoid sparks or unwanted discharge follow EN 61010-1 (chapter 6.7, Insulation requirements. Fig. 4, Tab. 6, Annex C).

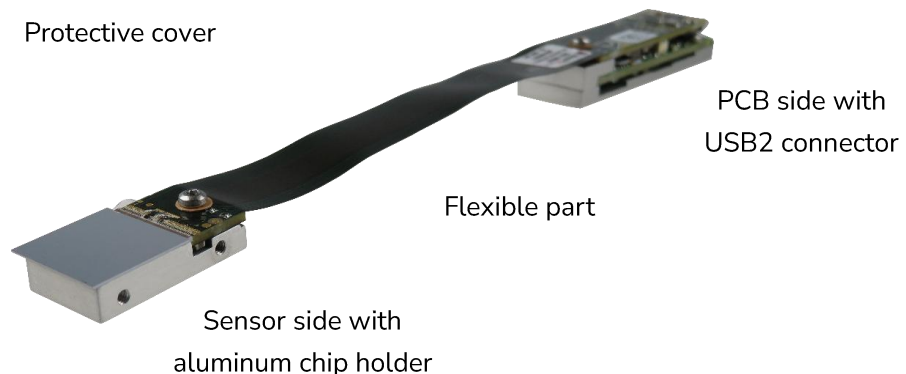
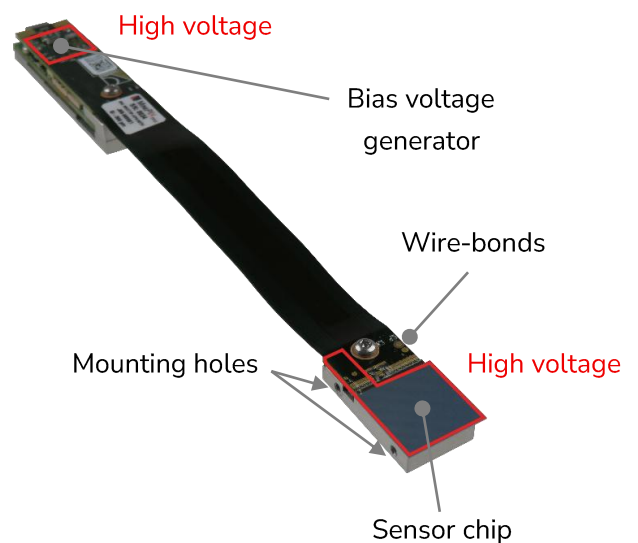
Device with protective plastic cover

(Left: as delivered, right: opened)



Plastic cover removed

(Before installation)



USB connector

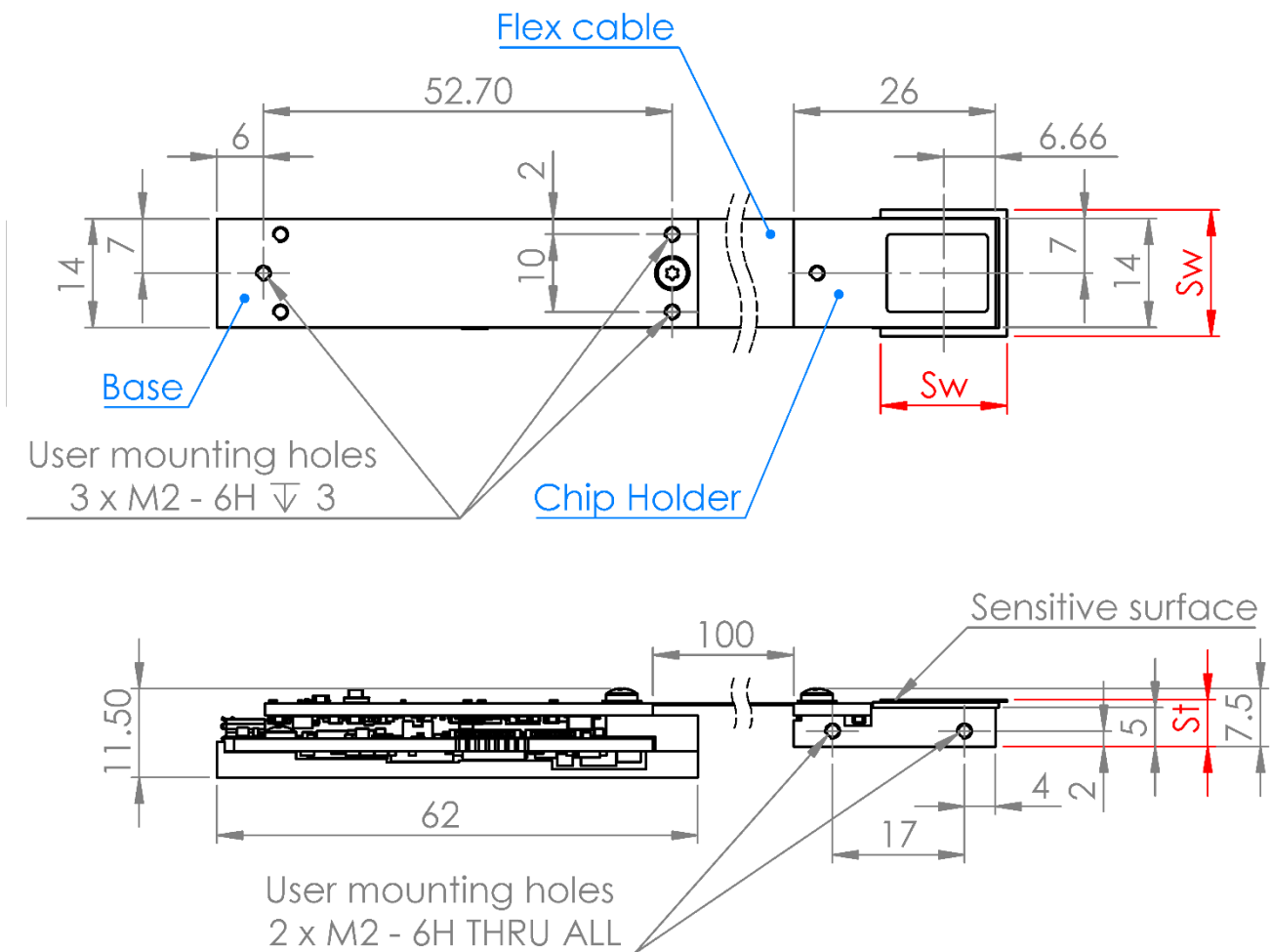
USB type Micro-B, Standard USB 2.0 High-Speed. The USB cable length should be less than 2m. For longer connections, a repeater or active cable is suggested.

Mechanical dimensions

MiniPIX versions: MNXT3F-Xxx190731; MT3Fxx-Xxx190925; MT3F10-Xxx211214

Mechanical dimensions for Si sensor.

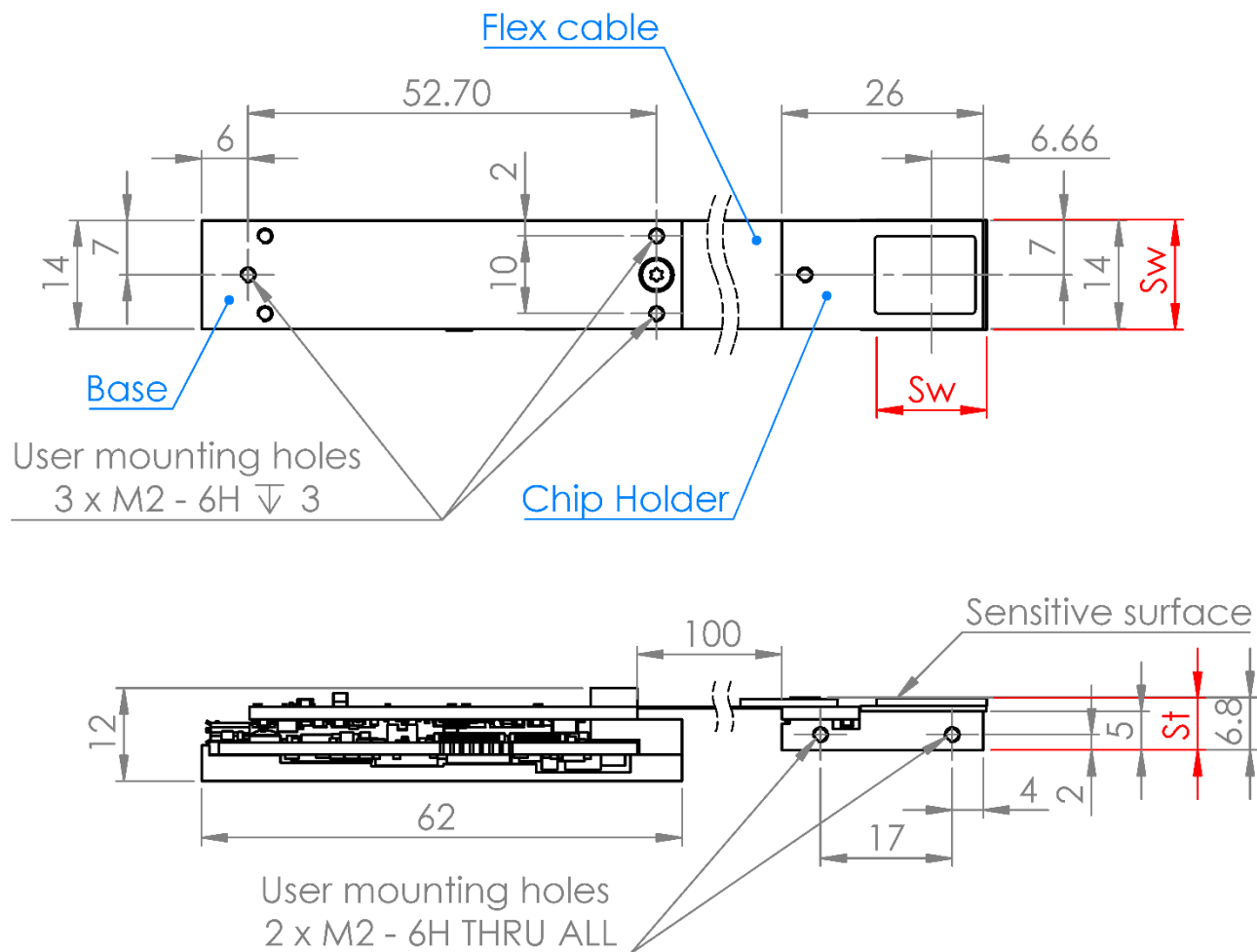
Drawing of the device with aluminum base supporting the PCB side:



MiniPIX versions: MNXT3F-Xxx190731; MT3Fxx-Xxx190925; MT3F10-Xxx211214

Mechanical dimensions for CdTe sensor.

Drawing of the device with aluminum base supporting the PCB side:

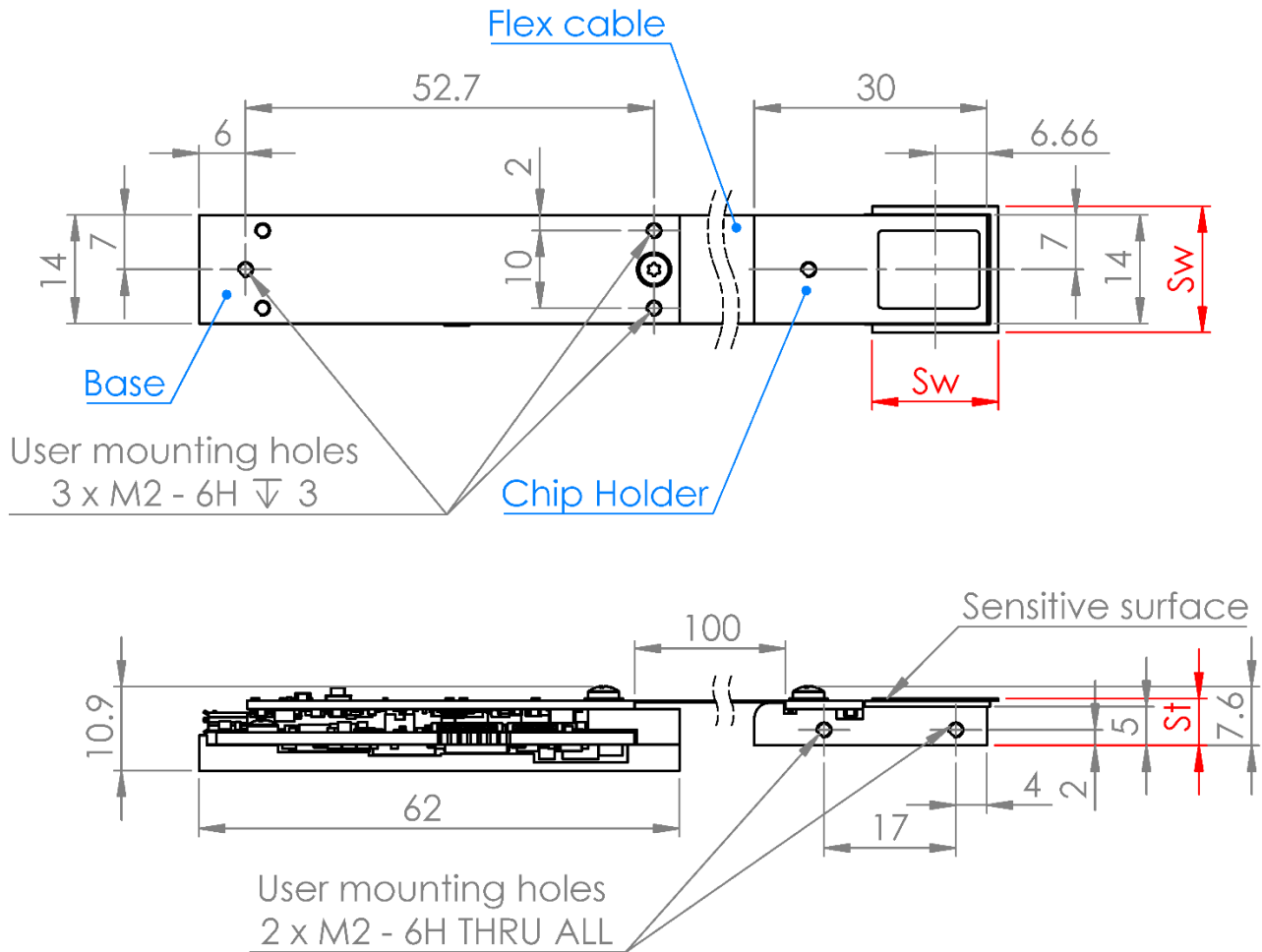


All dimensions are in mm. The sensor specific dimensions S_t and S_w (shown in red) are listed in the following table.

MiniPIX version: MT3F10-Xxx220422

Mechanical dimensions for Si sensor.

Drawing of the device with aluminum base supporting the PCB side:

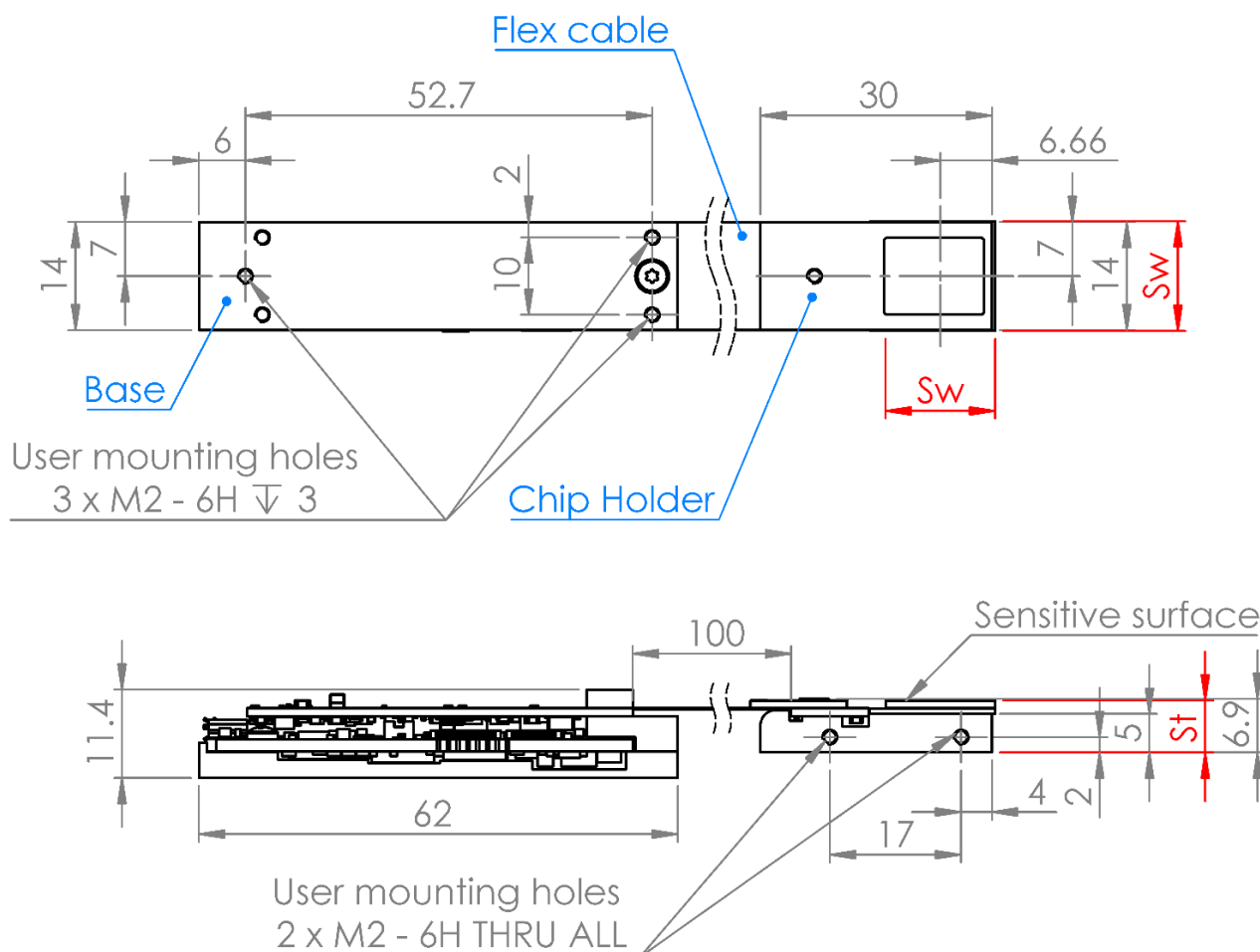


All dimensions are in mm. The sensor specific dimensions S_t and S_w (shown in red) are listed in the following table.

MiniPIX version: MT3F10-Xxx220422

Mechanical dimensions for CdTe sensor.

Drawing of the device with aluminum base supporting the PCB side:

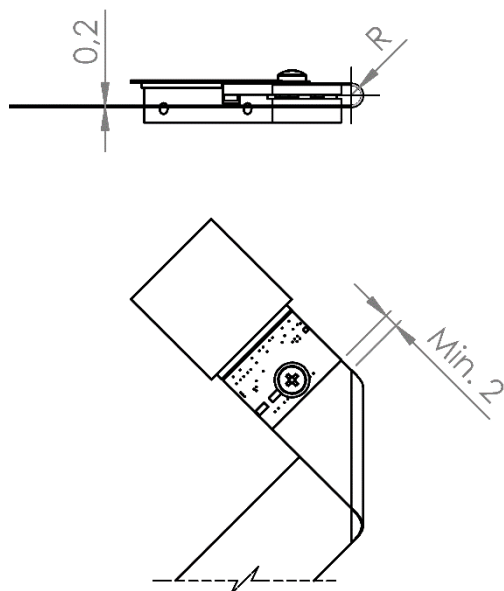


All dimensions are in mm. The sensor specific dimensions S_t and S_w (shown in red) are listed in the following table.



Extreme care must be taken when removing protecting cover and handling the MiniPIX MAGIC Flex without the protecting cover. Warranty does not apply to mechanical damage of the sensor and wirebonds.

Flex cable bending parameters



Bending radius according to IPC-2223 standard (2 layers flex PCB, 0,2 mm thick)

Bending type	Stable	Semi-Dynamic	Dynamic
Min. bending radius	2 mm	4 mm	30 mm

Sensor type specific dimensions

Sensor material	Sensor thickness [μm]	Model code	Module thickness s_t [mm]	Module width s_w [mm]
Si planar	100	MT3F10-XP1	5,84	15,45
	300	MT3F10-XP3	6,04	16,28
	500	MT3F10-XP5	6,24	16,28
CdTe	1000	MT3F10-XCA	6,74	14,185
	2000	MT3F10-XCB	7,74	14,185

Model number codes

Example: MT3 F10 - X P 3 XXXXXXXX

Device name:

MNX – MiniPIX

Device modification:

F10 – Flex cable length 100 mm

Sensor type:

P – Planar silicon
C – CdTe

Sensor thickness:

1 – 100 μm
3 – 300 μm
5 – 500 μm
A – 1000 μm
B – 2000 μm

Device build version:



Instructions for safe use



Remove plastic cover before use!
Attach the aluminum support to an appropriate heatsink!
Do not touch sensor surface or wire bonds!
Attention! Electrostatic-sensitive device!

The **MiniPIX MAGIC Flex** is designed as a component to be integrated into users' system. It is not designed for independent use. The minimum system requirements are:

- Proper heatsink attached to an aluminum sensor support,
- Mechanical cover of the whole device,

Electrical protection of the whole device: Avoid open access to bias voltage!

To avoid malfunction or damage to your **MiniPIX MAGIC Flex** please obey the following:

- Do not expose to water or moisture.
- Do not disassemble. Wire-bonding connection may be irreversibly damaged.
- Do not insert any object into the sensor window.
- The maximum USB cable length is 2 m.
- Thermal stabilization of the device is necessary. Recommended temperature is 22 °C.
- A direct connection to the host device is required for maximum performance. Connecting via a USB hub may negatively affect the performance and stability of the device.
- The protection provided by this product may be impaired if it is used in a manner not described in this document.

Disposal



Do not dispose these instruments as unsorted municipal waste. Please use separate collection facility to contact the supplier from which the instrument was purchased. Please make sure discarded electrical waste is properly recycled to reduce environmental impact.

Release history

Date (YY/MM/DD)	Changes	Changed by
19/04/12	Preliminary datasheet	
20/04/03	New version; Mechanical dimensions; Sensor parameters	
22/05/25	New version; Vacuum compatibility; Sensor parameters; ToA	
22/08/15	New version; new components	
24/03/27	Datasheet revision	J. Baborák
24/04/09	Measurement types	J. Baborák, D. Doubravová
24/05/24	New graphic style of the document	J. Baborák, P. Bloudek
24/06/07	Warning sign change	J. Baborák
24/06/12	Temperature stabilization instructions edited	J. Baborák
24/06/24	USB hub warning added	J. Baborák
24/07/23	Minor format changes	J. Baborák
26/03/02	New graphic style of the document, rebranding	P. Bloudek

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